

COMe 945 BASIC MODULES

Com Express[™] Family

- → Intel[®] Core[™] Duo L2400 (1.66GHz) or T2500 (2.0GHz)
- → Intel[®] 945GM Chipset with integrated Intel[®] Graphics Media Accelerator 950
- → Up to 2 GB PC2-4300 DDR2 SDRAM





COMe 945 B Core Duo Module



COM Express, an open specification of the PICMG (PCI Industrial Computer Manufacturer Group), is a module concept to bring PCI Express and other latest technologies like SATA, USB 2.0 and LVDS on a COM (Computer On Module).

COM Express is plugged onto an application-specific base board similar in the ETX concept, but offers more options and a growth path to future CPU technologies. Utilizing different sizes, COM Express can be used for highly embedded solutions up to high performance platforms.

The design of the COM 945 B module supports the dual core CPU technology enabling you to boost your embedded application to highest performance levels. For low power requirements we also support the LV-version in a single core configuration.

For evaluation and design-in of the COM Express modules we provide evaluation baseboards and develop motherboards providing the interface infrastructure for the COM Express module offering PC type connectors for external access.

Special Starter Kits for Linux are available on request. msc-ge.com

III Features

- → Intel Core Duo L2400 (1.66 GHz) or T2500 (2.0 GHz)
- ightarrow Intel 945GM Chipset with integrated Intel Graphics Media Accelerator 950
- → Up to 2 GB PC2-4300 DDR2 SDRAM
- → Two SATA-300 mass storage Interfaces
- → 10/100/1000 Base-TX Ethernet Interface
- → LVDS Interface (18 / 24 / 36 / 48 Bit)
- \rightarrow Resolution up to 2.048 x 1.536
- \rightarrow CRT Interface up to 2.048 x 1.536
- → Dual Independent Display supported
- → Four PCI Express x1 lanes
- → Eight USB 2.0 Interfaces
- \rightarrow AC'97 Audio Interface
- → RTC (Battery-buffered)
- → System Monitoring, Watchdog
- → APM ACPI Power Management including suspend-to-RAM
- → Fully COM Express Type 2 compliant
- → WindowsXP (embedded) and Linux supported

Product description	Clock	TDP
COMe Pentium M 745 Compact Module	1.80 GHz	26 Watt
COMe Pentium M LV 738 Compact Module	1.40 GHz	15 Watt

III Core Logic, Memory

EIDE

CPU	Intel Core Duo L2400 (1.66 GHz) or
	Intel Core Duo T2500 (2.0 GHz, upon request)
Chipset	Intel 82945GM, ICH7-M
Memory	200-pin SO-DIMM socket for up to 2 GB PC2-4300 SDRAM
III Drives	
SATA	2 SATA II channels up to 300 MB/s each

1 Enhanced IDE ports Ultra DMA100

III Standard Interfaces

8 x USB 2.0

III Bus Interfaces

COM Express Typ2 Interface, fully complient

III Interface

USB

PCI Express	Four channels, PCIe x1, one channel shared with Gbit
	Ethernet option
PCI	32 Bit standard interface
LPC	Low Pincount Bus for heritage interfaces Flat Panel / CRT
	Interfaces
Graphics	Intel Graphics Media Accelerator 950 Controller
	(integrated in Intel 945GM chipset)
Video Memory	UMA, up to 224 MB
LCD Interface	LVDS 24/48 Bit, dual channel via SVDO-to-LVDS converter
	Max. resolution 1.600 x 1.200 or
	external PCIe x16 graphic CRT Interface
	Max. resolution 2.048 x 1.536
TV out	Composite or S-Video

III Miscellaneous

Watchdog Timer	Creates system reset (programmable, 15 255h)
Fan Supply	3-pin header (5V) Battery External

AC'97 2.3 Audio Interface

III System Monitoring

Voltage	yes
Temperature	yes
Fan	yes

III LAN Interface

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Ethernet 10/100Base-TX (82562EZ) controller (Intel 82559
compatible) or 10/100/1000Base-TX (82573E)
LAN Boot RPL PXE
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III Sound Interface

Audio

III BIOS

Туре	Phoenix (in on-board Flash)
Auto	Plug & Play (PCIe)
Configuration	PCI Auto Configuration (PCI 2.1)
	Automatic DRAM configuration
Boot Options	Quick Boot MultiBoot (FD, HD, CD, LAN, USB)
	Boot without keyboard
Security	System and setup password Write protection for BIOS Flash
Power Management	APM ACPI (including suspend-to-RAM)
	Fixed frequency option (Setup)
	Geyserville 3 Support
USB	USB legacy support(Keyboard, Mouse, Hub)
Video	VGA Bios with flat panel extensions

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Flash Update	BIOS update via storage media
Setup	CMOS setup backup in EEPROM

III Power Supply

Power Power Consumption 30W typ. (1.66GHz, 256MB)

III Environment

Ambient	o° 6o°C (operating)
Temperature	-25° 85°C (storage)
Humidity	5 95% (operating, non-condensing)
	5 95% (storage, non-condensing)

Power +12V +/-10%, 5V Stby optional

III Mechanical

Dimensions 125mm x 95mm x13mm

